

PACKAGED MICROELECTRONIC DEVICES AND METHODS OF PACKAGING
MICROELECTRONIC DEVICES

ABSTRACT OF THE DISCLOSURE

Packaged microelectronic devices and methods of packaging microelectronic devices are disclosed herein. In one embodiment, the device includes an image sensor die having a first side with a bond-pad, an active area on the first side, and a second side opposite the first side. The device further includes a window at the first side of the image sensor die and a lead mounted to the second side of the image sensor die. The window is radiation transmissive and positioned over the active area of the image sensor die. The lead is electrically coupled to the bond-pad on the image sensor die.